

What is claimed is:

1 1. A semiconductor device comprising:
2 a plurality of electronic components including at least one
3 semiconductor integrated circuit chip, and a plurality of
4 intermediate substrates interposed between the electronic
5 components and a package and directly mounting said electronic
6 components on its one major face, wherein
7 each of said intermediate substrates has on said one major face
8 at least a plurality of first electrodes that are connected to
9 said electronic components, a plurality of second electrodes
10 for external connection and, and internal connection wirings
11 for connecting between said electronic components including
12 connection between said first electrodes and said second
13 electrodes.

1 2. The semiconductor device as claimed in claim 1, wherein at
2 least one of said electronic components is mounted straddling
3 over different ones of said intermediate substrates.

1 3. The semiconductor device as claimed in claim 1, wherein said
2 electronic components include a plurality of semiconductor
3 integrated circuit chips and at least one of said semiconductor
4 integrated circuit chip is mounted straddling over different
5 ones of said intermediate substrates.

1 4. The semiconductor device as claimed in claim 1, wherein said
2 package includes a printed circuit board having a first face

3 and a second face that are mutually in obverse and reverse relation,
4 and is equipped with a plurality of external connection
5 electrodes on said first face, equipped with a plurality of third
6 electrodes on said second face, and connects said external
7 connection electrodes and said third electrodes that are mutually
8 corresponding by means of wirings within the printed wiring board,
9 mounts all of said intermediate substrates on said second face,
10 and connects said second electrodes to said third electrodes
11 that are mutually corresponding.

1 5. A semiconductor device comprising:
2 a plurality of electronic components including at least one
3 semiconductor integrated circuit chip, intermediate substrates
4 directly mounting all of the electronic components on one major
5 face, and a package including a printed wiring board having a
6 first face and a second face that are in mutually obverse and
7 reverse relation, wherein
8 each of said intermediate substrates is equipped on said one
9 major face at least a plurality of first electrodes connected
10 to said electronic components, a plurality of second electrodes
11 for external connection, and internal connection wirings that
12 connect between said electronic components including the
13 connection between said first electrodes and said second
14 electrodes that are mutually corresponding,
15 said printed wiring board is equipped with a plurality of external
16 connection electrodes on said first face, equipped with a
17 plurality of third electrodes on said second face, and connects
18 said external connection electrodes and said third electrodes

19 that are mutually corresponding by means of wirings within the
20 printed wiring board, and
21 said one major face of each of said intermediate substrates is
22 placed facing the second face of said printed wiring board and
23 said second electrodes and said third electrodes that are
24 mutually corresponding are bonded.

1 6. The semiconductor device as claimed in claim 5, wherein said
2 printed wiring board is equipped with a recessed region in said
3 second face and the recessed region includes at least a region
4 which faces said electronic components mounted on said
5 intermediate substrates.

1 7. The semiconductor device as claimed in claim 5, wherein said
2 intermediate substrates and said printed wiring board are bonded
3 via bumps.

1 8. The semiconductor device as claimed in claim 1 or claim 5,
2 wherein the outer shape of said intermediate substrate is
3 rectangular and the length of either one side of the rectangle
4 is less than 20mm.